

SPECIFICATIONS

Mechanical

Durability: 10'000 cycles min.
Actuation force: 2.5kgf max.

Electrical

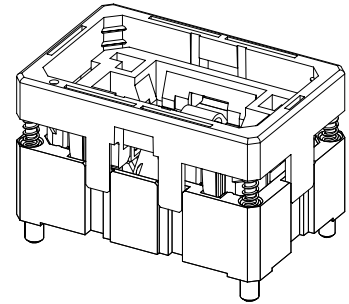
Current Rating: 1Amp/pin min.
Dielectric Withstanding Voltage: 650V A.C for 60 sec.
Insulation Resistance: 1000MΩ min.
Contact Resistance: 150mΩ max.
Hast: Pass 85 at 85% RH, 50 hours duration
Temperature cycling: Pass -55 to 125 , 1000 cycles
Bake : Pass 150 for 168 hours

Physical

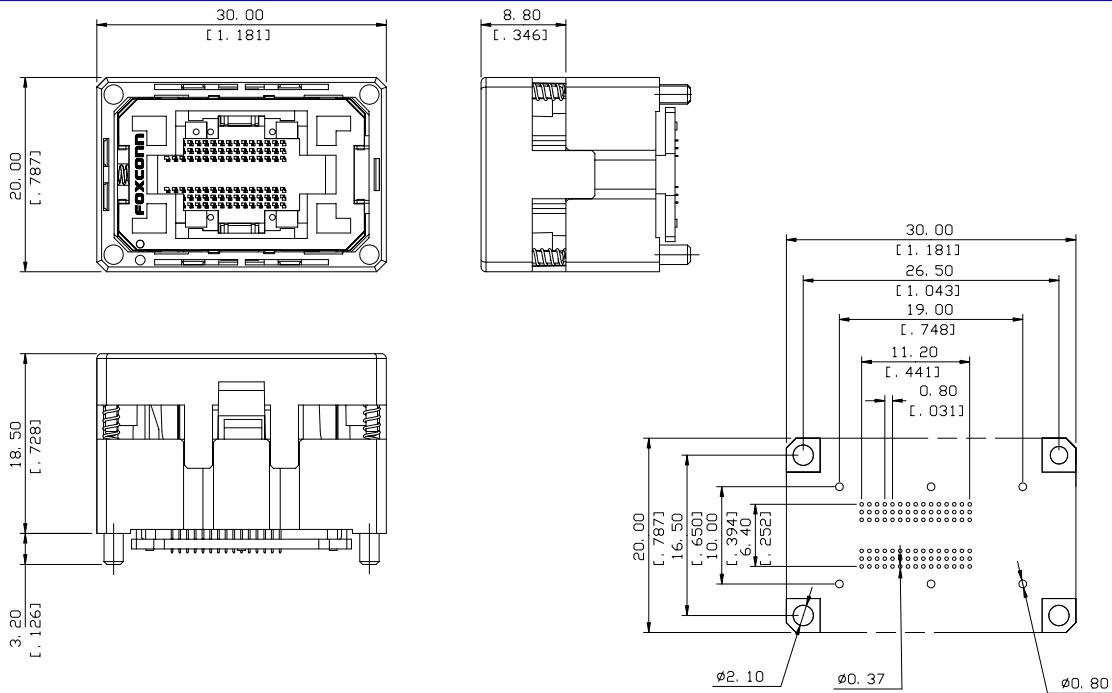
Cover & Base & Lid: Thermoplastic, UL 94V-0
Contact: Copper alloy
Contact Plating: See "ORDERING INFORMATION"
Operating Temperature: 150 max.

Burn-In & Test Socket

Burn-In Socket Series
BGA Type, Open Top, Type 2
0.80 mm [.031"] Pitch
90 Pos.



DRAWING



RECOMMENDED P. C. B. LAYOUT

ORDERING INFORMATION

PRODUCT NO.: 2 Q 0 0 * * 3 7 - 3 3 2 * - 1 0 F

Pin Counts
 0072=72 Pos.
 0090=90 Pos.

Tail Plating
 3=Au

Contact Plating
 7=15μ" Gold Plating

Chip/Burn-in Board
 3=BGA/PGA

Pitch
 3=0.80 mm

Design Type
 2=Type #2

LF Code
 F=Lead Free

Pick-up Design
 0=None

Package
 1=Soft Tray

Chip Spec.
 1=12.5x10.0
 4=11.5x11.0
 5=12.0x8.0
 A=10.5x11.5

2Q009037- 3325- 10F	90	12.0x8.0
2Q009037- 3324- 10F	90	11.5x11.0
2Q009037- 3321- 10F	90	12.5x10.0
2Q007237- 332A- 10F	72	19.5x11.5
2Q007237- 3321- 10F	72	12.5x10.0
P/N	POS.	CHIP SPEC.